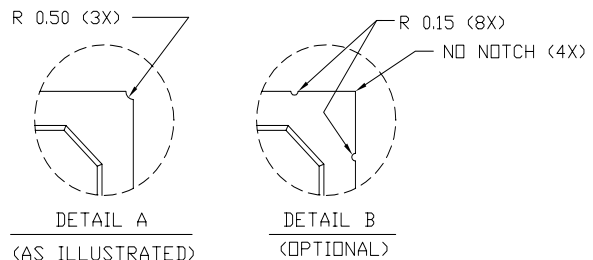


FG256 - 63/37 (Sn/Pb) Solder Balls  
 FGG256 - Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	$\approx$	$\approx$	2.00	3
A <sub>1</sub>	0.35	0.50	0.60	
D/E	17.00 BSC			
D <sub>1</sub> /E <sub>1</sub>	15.00 REF			
e	1.00 BSC			
$\phi_b$	0.50	0.60	0.70	2
aaa	$\approx$	$\approx$	0.20	
ccc	$\approx$	$\approx$	0.35	
ddd	$\approx$	$\approx$	0.30	
eee	$\approx$	$\approx$	0.10	
M	16			



### NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
2. SYMBOL 'M' IS THE BALL MATRIX SIZE
3. NOMINAL DIMENSION IS TYPICALLY 1.60-1.73mm
4. CONFORMS TO JEDEC MS-034-AAF-1

## 256-BALL FINE-PITCH BGA, 1.00MM PITCH (FG256/FGG256)